



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD60R145CFD7		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA002182514						
<b>Package</b>		PG-TO252-3-341		<b>Weight*</b>		389.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.851	1.24	1.24	12448	12448
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		191	
	non noble metal	iron	7439-89-6	0.248	0.06		638	
	non noble metal	copper	7440-50-8	248.124	63.69	63.77	636685	637514
	non noble metal	aluminium	7429-90-5	1.536	0.39	0.39	3941	3941
wire	non noble metal	aluminium	7429-90-5	1.536	0.39	0.39	3941	3941
encapsulation	organic material	carbon black	1333-86-4	0.380	0.10		976	
	plastics	epoxy resin	-	11.533	2.96		29595	
	inorganic material	silicondioxide	60676-86-0	114.827	29.46	32.52	294646	325217
leadfinish	non noble metal	tin	7440-31-5	3.740	0.96	0.96	9597	9597
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1306	1306
solder	non noble metal	tin	7440-31-5	0.078	0.02		200	
	noble metal	silver	7440-22-4	0.097	0.02		249	
	non noble metal	lead	7439-92-1	3.713	0.95	0.99	9528	9977
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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